WDS 520 Laser BGA Reballing Machine For Mobile Phone Laptop Motherboard

Basic Information

Place of Origin:	China
Brand Name:	WDS
Certification:	CE
Model Number:	WDS-520
Minimum Order Quantity:	1 UNIT
Packaging Details:	Wooden case
Delivery Time:	8-15 working days
Payment Terms:	T/T, Western Union, MoneyGram
Supply Ability:	150 UNITS PER MONTH

Product Specification

Application:	Rework BGA
Keyword:	Welding Robot China
Advantage:	Low Weight
Highlight:	**WDS 520 Laser BGA Reballing Machine**, **Laptop Motherboard Laser BGA Reballing Machine** , **WDS 520 Laser Reballing Machine**

Product Description

IR Preheater lead-free Infrared WDS-520 BGA Rework Station

Product Description

Our BGA Rework Station/BGA reballing station are widely used to replace and repair the BGA chip in laptop , mobile phone , xbox 360, ps3,etc. The main user is repairing shops and factory to provide the after-sales service and rework.

Manual BGA Rework Station
Model:WDS-520

Repair Success Rate:More Than 99%
Using The Industriak Touche Screen
Independent 3 Heating Zones, Hot Air Heating/ Infrared Preheat.(temperature accuracy ± 2°C)
With CE Certification

Main Features

Operation System

Manual mode.
Can solder, desolder, mount, pick and replace chip.
User-friendly.

Strict Temperature Control System

8 segments rising temperature/constant time/ temperature rising slope, it can save hundreds of groups temperature curve.
It adopts high accuracy K-type thermocouple close-loop control.
The external sensor can detect temperature precisely, analyze and calibrate the real temperature curve accurately at any time.

Safety Sustem

With CE cetification
With automatic power-off protection device when abnormal accident happens and double over-temp protection fuction.

Power supply	AC 220V ± 10% 50Hz
Total power	3800W
Heater power	Upper temp.zone 800W, second temp.zone 1200W, IR temp.zone 1800W(1200W controlled)
Electrical material	Touch screen+Temperature control module+ microcontrollers
Locating way	V-shape card slot + Universal jigs
PCB size	Max 300mm*280mm Min 10mm*10mm
Applicable chips	Max 60mm*60mm Min 1mm*1mm
PCB thickness	0 .3-5mm
Overall dimension	L460mm*W480mm*H500mm
Weight of machine	About 30KG
Usage	Repair chips/phone motherboard etc.